

03-29-2000

IN TH



TRADEMARK OFFICE

101300641

Attorney Docket No. 8693-000196

COVER SHEET FOR RECORDAL OF DOCUMENT (PATENT)

3.17.00

Hon. Commissioner of Patents and Trademarks
Washington, D.C. 20231

JCS25 U.S. PTO
09/531108
03/17/00

Sir:

Pursuant to 37 C.F.R. 3.31, enclosed herewith is a document for recordal in this case.
The following information is provided:

(1) **Name Of Party Conveying The Interest:**

Edberg Fang
Wen-Yi Hsieh
Teng-Chun Tsai

(2) **Name And Address Of Party Receiving The Interest:**

UNITED MICROELECTRONICS CORP.
No. 3, Li-Hsin Rd. 2, Science-Based Industrial Park
Hsin-Chu City, TAIWAN, R.O.C.

(3) **Description Of The Transaction To Be Recorded:**

☒ Assignment ☐ License
☐ Change of Name ☐ Other _____

03/27/2000 ASELLMAN 00000124 09531108
03 FC:561 (4) (40.00 DP)

Application(s) and/or Patent(s) Against Which Enclosure Is To Be Recorded:

☐ Serial Number 09/531108, filed _____
☒ Application being filed concurrently herewith.
☐ Patent Number _____, issued _____

(5) **Name And Address Of The Party To Whom Correspondence Concerning The Request To Record Should Be Mailed:**

Thomas T. Moga
HARNESS, DICKEY & PIERCE, P.L.C.
P.O. Box 828
Bloomfield Hills, MI 48303

(6) **Number Of Applications and/or Patents Identified In The Cover Sheet And Total Recordal Fee:**

Number of Applications/Patents: . . . 1


Total Recordal Fee Enclosed: . . . \$40.00

(7) **Date(s) The Document Was Executed:** February 29 and March 1, 2000

To the best of my knowledge and belief, the foregoing information is true and correct, and if the attached is not an original document, the undersigned verifies that it is a true copy of the original.

If, for some reason, Applicants have not paid a sufficient fee, please charge our Deposit Account No. 08-0750 for any further fees which may be due. A duplicate copy of this document is enclosed.

Respectfully submitted,

By: 
Thomas T. Moga
Registration No. 34,881
Attorney for Applicants

Date: March 17, 2000

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Edberg FANG

(4)

(2) Wen-Yi HSIEH

(5)

(3) Teng-Chun TSAI

(6)

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

UNITED MICROELECTRONICS CORP.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD FOR FORMING BRIDGE FREE SILICIDE

[a] for which an application for United States Letters Patent was filed on, and identified by United States Serial No.; or

[b] for which an application for United States Letters Patent was executed on, February 29 and March 1, 2000

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS

DATE SIGNED

(1) *Edberg Fang**Feb. 29. 2000*

Name: Edberg FANG

(2) *Wen-Yi Hsieh**Mar. 1. 2000*

Name: Wen-Yi HSIEH

(3)

Name: Teng-Chun TSAI

(4) *Teng-Chun Tsai**Feb. 29. 2000*

Name: